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Abstract

Semiconductor component and method for producing it

The invention relates to a semiconductor component 28, in particular memory module, having a carrier board 16 and having a plurality of semiconductor chips 1, in particular memory chips, the semiconductor chips 1 being fitted on the carrier board 16 in such a way that the main planes 19 thereof run perpendicular to the carrier boards 16. Furthermore, the invention relates to a method for producing semiconductor components 28.

(Fig. 4)

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